

## 4.0x0.8mm RIGHT ANGLE SMD LED

Part Number: KA-4008SESK Super Bright Orange

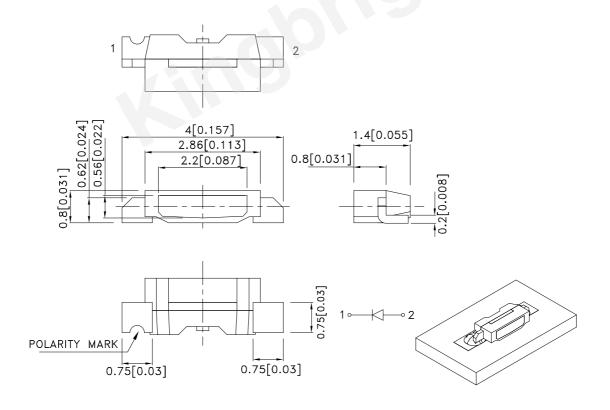
### **Features**

- 4.0mmX0.8mm SMT LED, 1.4mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

## **Description**

The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

## **Package Dimensions**



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.1(0.004")$  unless otherwise noted.
- 3.The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
  4.The device has a single mounting surface. The device must be mounted according to the specifications.





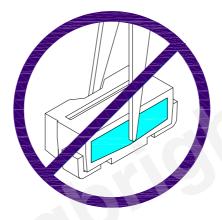
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## **Handling Precautions**

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



2. As silicone encapsulation is permeable to gases, some corrosive substances such as  $H_2S$  might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website. <a href="http://www.kingbright.com/application\_notes">http://www.kingbright.com/application\_notes</a>

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## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KA-4008SESK	Super Bright Orange (AlGaInP)	Water Clear	200	300	120°
KA-4000SESK			*80	*160	

### Notes:

- 1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
   Luminous intensity value is traceable to the CIE127-2007 compliant national standards

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	IF=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	IF=20mA
lr	Reverse Current	Super Bright Orange		10	uA	V <sub>R</sub> =5V

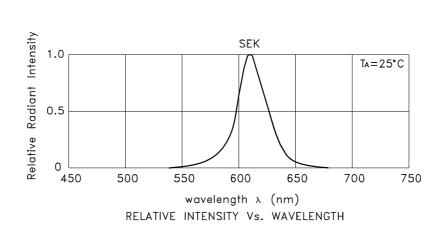
- Notes:
  1.Wavelength: +/-1nm.
  2. Forward Voltage: +/-0.1V.
  3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

### Absolute Maximum Ratings at TA=25°C

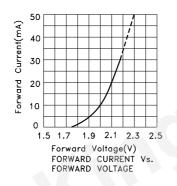
7.000 late maximum ratings at 171 20 0					
Parameter	Super Bright Orange	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	195	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

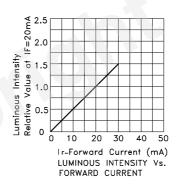
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

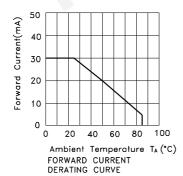
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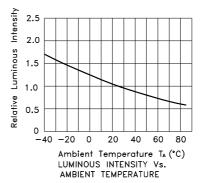


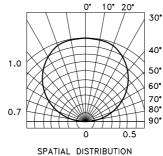
Super Bright Orange KA-4008SESK











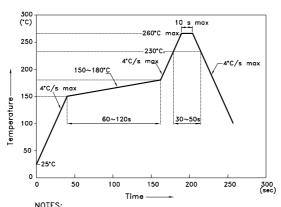
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## **KA-4008SESK**

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



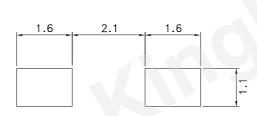
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- to high temperature.

  3.Number of reflow process shall be 2 times or less.

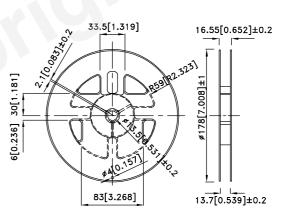
## Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

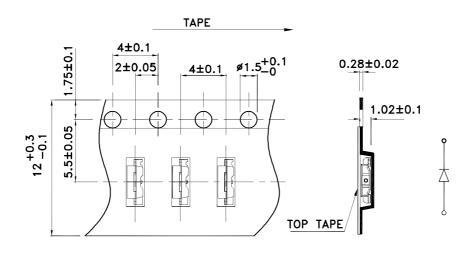


## Tape Dimensions

(Units: mm)

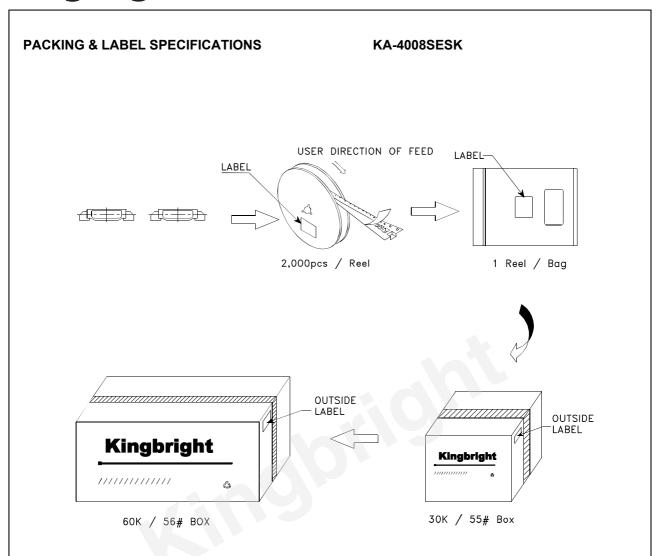
## **Reel Dimension**

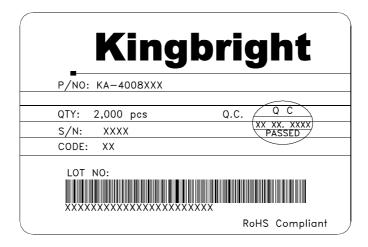




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